



# of Materi

TI DESIGNS

TIPD131: Single-Ended Input to Differential Output Conversion Circuit

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number 1
1	1	10uF	C1	CAP, TANT, 10uF, 20V, 20%, 1 ohm, 3528-21 SMD	AVX	TPSB106M020R1000	478-4087-1-ND
2	2	0.1uF	C2, C3	CAP, CERM, 0.1uF, 50V, 10%, X7R, 0603	MuRata	GRM188R71H104KA93D	490-1519-1-ND
3	10		J1, J2, J3, J4, J6, J7, J8, J9, J11, J12	JACK NON-INSULATED .218" Keystone"	575-4	575-4K-ND	
4	5		J2, J4, J7, J9, J12	JACK NON-INSULATED .218" Keystone"	575-4	575-4K-ND	
5	3		J5, J10, J13	BNC Connector	TE Connectivity	1-1478032-0	A97560-ND
6	6	49.9k	R1, R2, R3, R4, R5, R6	RES, 49.9k ohm, 0.1%, 0.1W, 0603	Panasonic	ERA-3AEB4992V	P49.9KDBCT-ND
7	1	Vcc	TP1	Test Point, TH, Compact, Red	Keystone	5005	5005K-ND
8	1	Black	TP2	Test Point, TH, Compact, Black	Keystone	5006	5006K-ND
9	4	Yellow	TP6, TP7, TP8, TP9	Test Point, TH, Compact, Yellow	Keystone	5009	5009K-ND
10	1	LF353M	U1	1.8V, 17uA, microPower, Precision, Zero Drift CMOS Op Amp	Texas Instruments	OPA2333AID	296-19543-5-ND
11	4		U90, U91, U92, U93	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH	H542-ND

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